

DECLARATION FOR PATENT APPLICATION (JOINT OR SOLE)

(Under 37 CFR § 1.63; with Power of Attorney)

FROMMER LAWRENCE & HAUG LLP

FLH File No. 450117-03700

As a below named inventor, I hereby declare that:
My residence, post office address and citizenship are as stated below next to my name,
I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention ENTITLED:

HYBRID SOLAR CELLS WITH THERMAL DEPOSITED SEMICONDUCTIVE OXIDE LAYER

the specification of which

X is attached hereto.

_____ was filed on _____ as Application Serial No. _____,

with amendment(s) through _____ (if applicable, give dates).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)	(List additional applications on separate page):	Priority Claimed:
Number:	Country:	Filed (Day/Month/Year):
00 125 784.9	Europe	24 November 2000
		Yes <u>X</u> No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U.S. Application(s)	(List additional applications on separate page):	Status (patented, pending, abandoned):
Appl. Ser. Number:	Filed (Day/Month/Year):	

I hereby appoint WILLIAM S. FROMMER, Registration No. 25,506, and DENNIS M. SMID, Registration No. 34,930 or their duly appointed associate, my attorneys, with full power of substitution and revocation, to prosecute this application, to make alterations and amendments therein, to file continuation and divisional applications thereof, to receive the Patent, and to transact all business in the Patent and Trademark Office and in the Courts in connection therewith, and specify that all communications about the application are to be directed to the following correspondence address:

WILLIAM S. FROMMER, Esq.
c/o FROMMER LAWRENCE & HAUG LLP
745 Fifth Avenue
New York, New York 10151

Direct all telephone calls to:
(212) 588-0800
to the attention of:
WILLIAM S. FROMMER

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

INVENTOR(S):

Signature: [Signature] Date: 21/11/01
Full name of sole or first inventor: Gabrielle NELLES

Residence: X Stuttgart, Germany
Citizenship: X Germany

Signature: [Signature] Date: 23/11/01
Full name of 2nd joint inventor (if any): Akio YASUDA

Residence: X Stuttgart, Germany

Citizenship: X Japan

Signature: [Signature] Date: 07/01/02
Full name of 3rd joint inventor (if any): Hans-Werner SCHMIDT

Residence: X Bayreuth, Germany
Citizenship: X Germany

[Similarly list additional inventors on separate page]
Post Office Address(es) of inventor(s):
[if all inventors have the same post office address]

SONY International (Europe) GmbH
c/o Advanced Technology
Center Stuttgart
Heinrich-Hertz-Strasse 1
70327 Stuttgart
GERMANY

Note: In order to qualify for reduced fees available to Small Entities, each inventor and any other individual or entity having rights to the invention must also sign an appropriate separate "Verified Statement (Declaration) Claiming [or Supporting a Claim by Another for] Small Entity Status" form [e.g. for Independent Inventor, Small Business Concern, Nonprofit Organization, individual Non-Inventor].

Note: A post office address must be provided for each inventor.

ADDITIONAL INVENTORS

FLH File No. 450117-03700

Signature: [Signature] Date: 20/12/01
 Full name of 4th joint inventor (if any): Mukundan THELAKKAT
 Residence: Bayreuth, Germany
 Citizenship: India

Signature: [Signature] Date: 17/12/01
 Full name of 5th joint inventor (if any): Christoph SCHMITZ
 Residence: Frankfurt/Main, Germany
 Citizenship: Germany

**RECORDATION FORM COVER SHEET
PATENTS ONLY**

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies)</p> <p>Gabrielle NELLES, Akio YASUDA, Hans-Werner SCHMIDT, Mukundan THELAKKAT, Christoph SCHMITZ</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and address of receiving party(ies)</p> <p>Name: SONY International (Europe) GmbH Kemperplatz 1 D-10785 Berlin GERMANY</p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
<p>3. Nature of conveyance:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Security Agreement <input type="checkbox"/> Merger <input type="checkbox"/> Change of Name <input type="checkbox"/> Other</p> <p>Execution Date(s): <u>November 23, November 23, 2001, January 7, 2002, December 20 and December 17, 2001</u></p>	

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:


A. Patent Application No.(s) 09/989,848 filed November 21, 2001

Additional numbers attached? ☐ Yes ☒ No

<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: WILLIAM S. FROMMER</p> <p>Internal Address: FROMMER LAWRENCE & HAUG LLP</p> <p>Street Address: 745 FIFTH AVENUE</p> <p>City: <u>NEW YORK</u> State: <u>N.Y.</u> Zip: <u>10151</u></p>	<p>6. Total number of applications and patents involved <u>1</u></p> <hr/> <p>7. Total fee (37 CFR 3.41) \$ <u>40.00</u></p> <p align="center"><input checked="" type="checkbox"/> Enclosed <input type="checkbox"/> Authorized to be charged to deposit account 50-0320</p> <hr/> <p>8. Deposit account number: (Attach duplicate copy of this page if paying by deposit account)</p>
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9. Statement and signature.
 To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

<u>WILLIAM S. FROMMER</u> Name of Person Signing	 Signature	<u>February 1, 2002</u> Date
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Total number of pages including cover sheet, attachments, and document: 3

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
 Box Assignments
 Washington, D.C. 20231

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WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

HYBRID SOLAR CELLS WITH THERMAL DEPOSITED SEMICONDUCTIVE OXIDE LAYER

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY International (Europe) GmbH, a German corporation, with offices at Kemperplatz 1, D-10785 Berlin, GERMANY (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

Gabrielle NELLES

Name of first or sole inventor

Execution date of U.S. Patent Application

X Stuttgart, Germany
Residence of first or sole inventor

Gabrielle Nelles

Signature of first or sole inventor

Date of this assignment

Akio YASUDA

Name of second inventor

Execution date of U.S. Patent Application

X Stuttgart, Germany
Residence of second inventor

Akio Yasuda

23/11/07

Signature of second inventor

Date of this assignment

Hans-Werner SCHMIDT

Name of third inventor

Execution date of U.S. Patent Application

X Bayreuth, Germany
Residence of third inventor

Hans-Werner Schmidt

07/01/02

Signature of third inventor

Date of this assignment

Mukundan THELAKKAT

Name of fourth inventor

Execution date of U.S. Patent Application

☒ Bayreuth, Germany

Residence of fourth inventor

20-12-01

Signature of fourth inventor

Date of this assignment

Christoph SCHMITZ

Name of fifth inventor

Execution date of U.S. Patent Application

☒ Frankfurt/Main, Germany

Residence of fifth inventor

17/12/01

Signature of fifth inventor

Date of this assignment